



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2822
#7/A
BLL
8-2103

In re the Application of: Bojkov, et al.

Conf. No.: 2251

Docket No.: TI-33887

Serial No.: 10/086,117

Examiner: Lewis, Monica

Filed: 02/26/02

Art Unit: 2822

For: Waferlevel Method for Direct Bumping on Copper Pads in Integrated Circuits

Amendment under 37 CFR 1.111

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

8-8-03

Michael K. Skrehot

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 05/08/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

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AUG 18 2003
TECHNOLOGY CENTER 2800